



## Material Content Data Sheet



<b>Sales Product Name</b>				IPG16N10S4-61		<b>Issued</b>		4. July 2019	
<b>MA#</b>				MA004080396					
<b>Package</b>				PG-TDSON-8-4		<b>Weight*</b>		96.06 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	0.692	0.72	0.72	7203	7203	
chip_2	inorganic material	silicon	7440-21-3	0.692	0.72	0.72	7203	7203	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		139		
	non noble metal	iron	7439-89-6	0.044	0.05		463		
wire	non noble metal	copper	7440-50-8	44.409	46.23	46.29	462310	462912	
	non noble metal	aluminium	7429-90-5	0.801	0.83	0.83	8341	8341	
encapsulation	organic material	carbon black	1333-86-4	0.092	0.10		955		
	plastics	epoxy resin	-	6.511	6.78		67781		
leadfinish	inorganic material	silicondioxide	60676-86-0	39.249	40.86	47.74	408594	477330	
	non noble metal	tin	7440-31-5	1.308	1.36	1.36	13613	13613	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	500	501	
solder	non noble metal	tin	7440-31-5	0.039	0.04		407		
	noble metal	silver	7440-22-4	0.049	0.05		509		
heatspreader	non noble metal	lead	7439-92-1	1.866	1.94	2.03	19427	20343	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
*deviation	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.245	0.26	0.26	2550	2554	
Sum in total:						100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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